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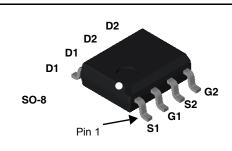
**ON Semiconductor®** 

# FDS8949 Dual N-Channel Logic Level PowerTrench<sup>®</sup> MOSFET

## **40V, 6A, 29m**Ω

#### Features

- Max  $r_{DS(on)} = 29m\Omega$  at V<sub>GS</sub> = 10V
- Max r<sub>DS(on)</sub> = 36mΩ at V<sub>GS</sub> = 4.5V
- Low gate charge
- High performance trench technology for extremely low <sup>r</sup>DS(on)
- High power and current handling capability
- RoHS compliant



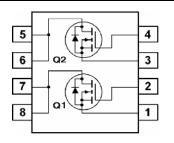
#### General Description

These N-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench<sup>®</sup> process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

#### Applications

- Inverter
- Power suppliers



### MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V <sub>DS</sub>	Drain to Source Voltage		40	V	
V <sub>GS</sub>	Gate to Source Voltage		±20	V	
ID	Drain Current -Continuous	(Note 1a)	6	— A	
	-Pulsed		20		
E <sub>AS</sub>	Drain-Source Avalanche Energy	(Note 3)	26	mJ	
P <sub>D</sub>	Power Dissipation for Dual Operation		2		
	Power Dissipation for Single Operation	(Note 1a)	1.6	W	
		(Note 1b)	0.9		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to 150	°C	
Therma	I Characteristics				
$R_{ hetaJA}$	Thermal Resistance-Single operation, Junction to Ambient	(Note 1a)	81	°C/W	
$R_{ hetaJA}$	Thermal Resistance-Single operation, Junction to Ambient	(Note 1b)	135		
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40		

### Package Marking and Ordering Information

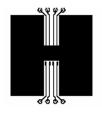
Device Marking	Device	Reel Size	Tape Width	Quantity
FDS8949	FDS8949	13"	12mm	2500 units

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Symbol	Parameter	Test Conditions	Min	Тур	Мах	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$ , referenced to 25°C		33		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 32V, V_{GS} = 0V$ $T_1 = 55^{\circ}C$			1 10	μA μA
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 V, V_{DS} = 0 V$			±100	nA
On Chara	acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA	1	1.9	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$ , referenced to $25^{\circ}C$		-4.6		mV/°C
r <sub>DS(on)</sub>	Drain to Source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6A		21	29	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4.5A		26	36	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 6A,T <sub>J</sub> = 125°C		29	43	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10V,I <sub>D</sub> = 6A		22		S
<b>Dynamic</b> C <sub>iss</sub>	Characteristics			715	955	pF
	Output Capacitance	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz		105	140	pF
C <sub>oss</sub> C <sub>rss</sub>	Reverse Transfer Capacitance			60	90	pF
R <sub>g</sub>	Gate Resistance	f = 1MHz		1.1	30	Ω
	g Characteristics	- ·····				
t <sub>d(on)</sub>	Turn-On Delay Time			9	18	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 20V, I <sub>D</sub> = 1A V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 6Ω		5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			23	37	ns
t <sub>f</sub>	Fall Time			3	6	ns
Q <sub>g</sub>	Total Gate Charge			7.7	11	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DS</sub> = 20V, I <sub>D</sub> = 6A,V <sub>GS</sub> = 5V		2.4		nC
Q <sub>gd</sub>	Gate to Drain "Miller"Charge			2.8		nC
	urce Diode Characteristics a	nd Maximum Ratinos				
V <sub>SD</sub>	Source to Drain Diode Forward Volta			0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time (note 3)			17	26	ns
Q <sub>rr</sub>	Reverse Recovery Charge	——I <sub>F</sub> = 6A, d <sub>iF</sub> /d <sub>t</sub> = 100A/μs		7	11	nC

 $\mathsf{Q}_{\mathsf{rr}}$ Notes:

1: R<sub>0JA</sub> is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.



**a)** 81°C/W when mounted on a 1in<sup>2</sup> pad of 2 oz copper

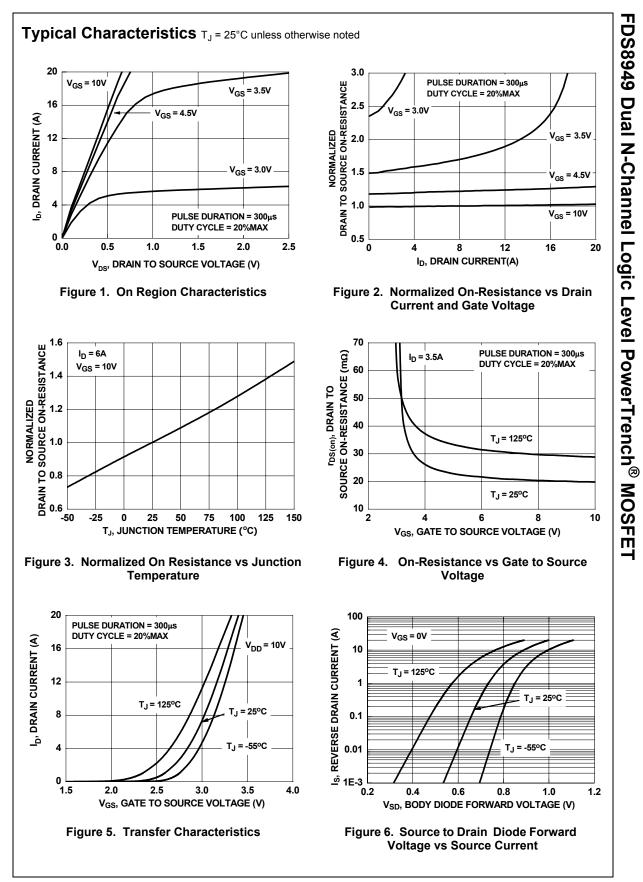
**b)** 135°C/W when mounted on a minimum pad .

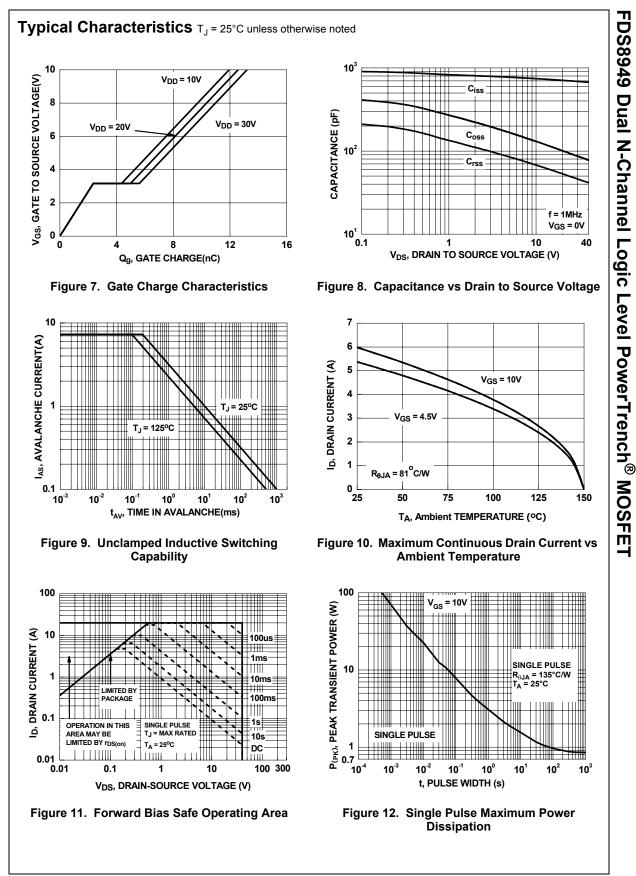
Scale 1:1 on letter size paper

2: Pulse Test: Pulse Width < 300 us, Duty Cycle < 2.0%.

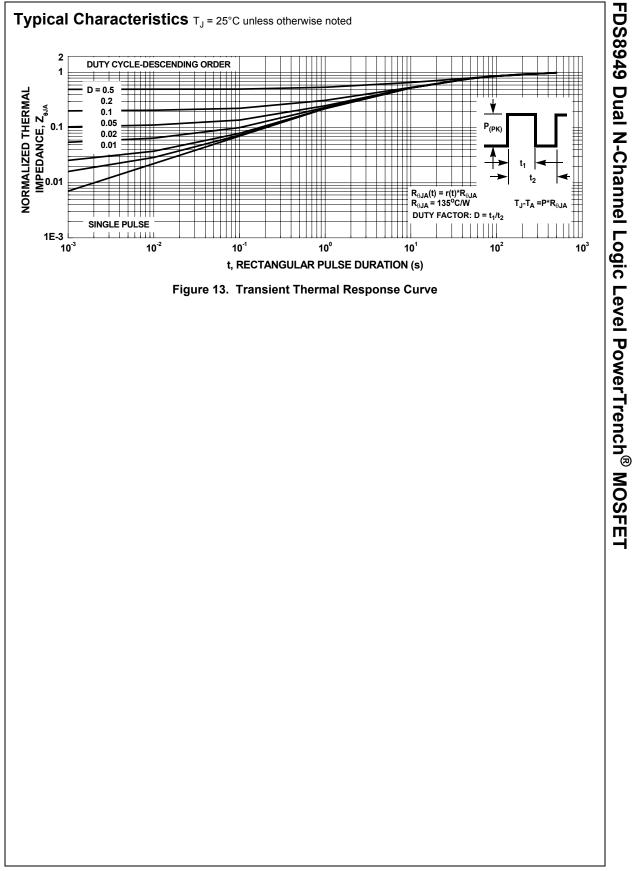
**3:** Starting  $T_J$  = 25°C, L = 1mH, I<sub>AS</sub> = 7.3A, V<sub>DD</sub> = 40V, V<sub>GS</sub> = 10V.

Reverse Recovery Charge





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